

具有三态输出的四路 2 线至 1 线数据选择 RS/多路复用器

1 特性

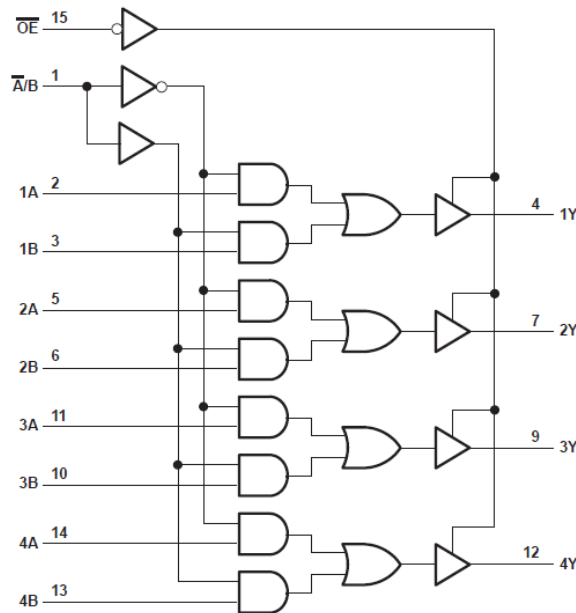
- 4.5V 至 5.5V 的工作电压范围
- 高电流三态输出直接与系统总线相连
- t_{pd} 典型值 = 17ns
- 低功耗, I_{CC} 最大值为 80 μ A
- 电压为 5V 时, 输出驱动为 ± 6 mA
- 低输入电流, 最大值 1 μ A
- 输入兼容 TTL 电压
- 在高性能系统中提供多个来源的总线接口
- 缓冲输入和输出

2 说明

'HCT257 器件旨在将 4 位数据源的信号多路复用到总线式系统中的 4 路输出数据线。

器件信息

可订购 器件型号	封装	封装尺寸 (标称值)
SN74HCT257	N (PDIP , 16)	19.31mm × 6.35mm
	D (SOIC , 16)	9.90mm × 3.90mm
SNJ54HCT257	J (CDIP , 16)	24.38mm × 6.92mm



A. 所示引脚编号适用于 D、J 和 N 封装。

逻辑图 (正逻辑)



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3 Revision History

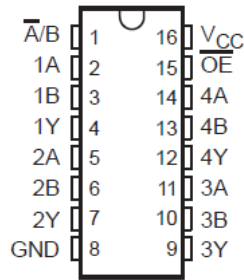
注：以前版本的页码可能与当前版本的页码不同

Changes from Revision D (September 2003) to Revision E (July 2022)

Page

- 更新了整个文档中的编号、格式、表格、图和交叉参考，以反映现代数据表标准..... 1

4 Pin Configuration and Functions



**图 4-1. J, N and D Package
 16-Pin CDIP, PDIP or SOIC
 Top View**

Pin Functions

PIN		I/O ⁽¹⁾	DESCRIPTION
SOIC or TSSOP NO.	NAME		
1	\bar{A}/B	I	Address select
2	1A	I	Channel 1, data input A
3	1B	I	Channel 1, data input B
4	1Y	I	Channel 1, data output
5	2A	O	Channel 2, data input A
6	2B	O	Channel 2, data input B
7	2Y	I	Channel 2, data output
8	GND	—	Ground
9	3Y	I	Channel 3, data output
10	3B	I	Channel 3, data input B
11	3A	I	Channel 3, data input A
12	4Y	I	Channel 4, data output
13	4B	I	Channel 4, data input B
14	4A	I	Channel 4, data input A
15	\bar{G}	I	Output strobe, active low
16	V _{CC}	—	Positive supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	7	V
I _{IK}	Input clamp current ⁽²⁾	V _I < 0 or V _I > V _{CC}	±20	mA
I _{OK}	Output clamp current ⁽²⁾	V _O < 0 or V _O > V _{CC}	±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}	±35	mA
	Continuous current through V _{CC} or GND		±70	mA
T _J	Junction Temperature		150	°C
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions⁽¹⁾

		SN54HCT257			SN74HCT257			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 4.5 V to 5.5 V		2	2			V
V _{IL}	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V		0.8		0.8		V
V _I	Input voltage	0	V _{CC}		0	V _{CC}		V
V _O	Output voltage	0	V _{CC}		0	V _{CC}		V
t _t	Input transition (rise and fall) time			500	500			ns
T _A	Operating free-air temperature	-55	125		-40	85		°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

5.3 Thermal Information

THERMAL METRIC		D (SOIC)	N (PDIP)	UNIT
		16 PINS	16 PINS	
R _{θJA}	Package thermal impedance	73	67	°C/W

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HCT257		SN74HCT257		UNIT
					MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	High level output voltage	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4	V	
					3.98	4.3		3.7		3.84		
V _{OL}	L Low level output voltage	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	4.5 V	0.001	0.1		0.1		0.1	V	
					0.17	0.26		0.4		0.33		

5.4 Electrical Characteristics (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HCT257		SN74HCT257		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I _I	Input leakage current	V _I = V _{CC} or 0	5.5 V	±0.1	±100		±1000	±1000	nA	
I _{OZ}	Off-State (High-Impedance State) Output Current	V _O = V _{CC} or 0, V _I = V _{IH} or V _{IL}	5.5 V	±0.01	±0.5		±10	±5	μA	
I _{CC}	Supply current	V _I = V _{CC} or 0, I _O = 0	5.5 V		8		160	80	μA	
ΔI _{CC} ⁽²⁾	Supply-Current Change	One input at 0.5 V or 2.4 V, Other inputs at 0 or V _{CC}	5.5 V	1.4	2.4		3	2.9	mA	
C _i	Input Capacitance		4.5 V to 5.5 V	3	10		10 ⁽¹⁾	10	pF	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

5.5 Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HCT257		SN74HCT257		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	4.5 V		20	30		45		38	ns
			5.5 V		17	27		40		34	
	A̅/B	Y	4.5 V		20	30		45		38	
			5.5 V		17	27		40		34	
t _{en}	OE̅	Y	4.5 V		20	30		45		38	ns
			5.5 V		17	27		40		34	
t _{dis}	OE̅	Y	4.5 V		20	30		45		38	ns
			5.5 V		17	27		40		34	
t _t		Any	4.5 V		8	15		22		19	ns
			5.5 V		7	14		21		17	

5.6 Switching Characteristics

over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see [Figure 6-1](#))

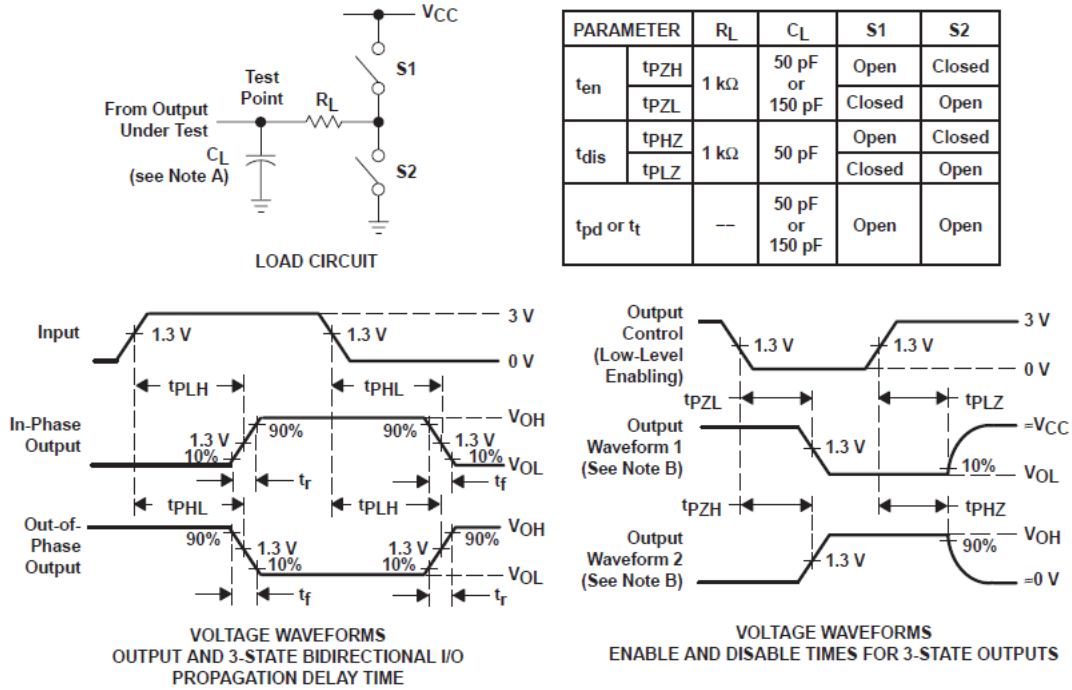
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	T _A = 25°C			SN54HCT257		SN74HCT257		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	4.5 V		22	38		57		48	ns
			5.5 V		19	35		53		44	
	A̅/B	Y	4.5 V		22	38		57		48	
			5.5 V		19	35		53		44	
t _{en}	OE̅	Y	4.5 V		23	40		60		50	ns
			5.5 V		20	38		57		48	
t _t		Any	4.5 V		17	42		63		53	ns
			5.5 V		14	38		57		48	

5.7 Operating Characteristics

 T_A 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load	13	pF

6 Parameter Measurement Information



- A. C_L includes probe and test-fixture capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. t_{PZL} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

图 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The 'HCT257 devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{OE}) input is at the high logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

7.2 Functional Block Diagram

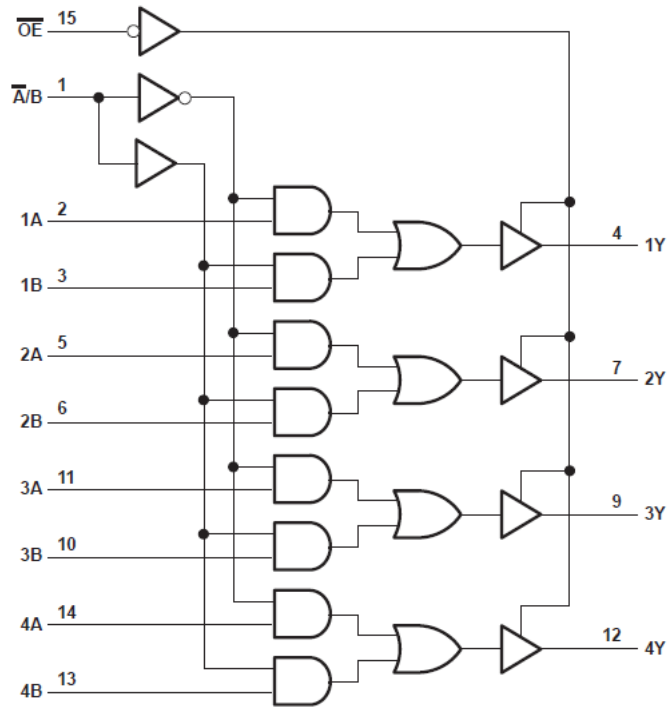


图 7-1. Function Diagram

8 Device Functional Modes

表 8-1. Function Table

INPUTS ⁽¹⁾				OUTPUT ⁽²⁾ Y
OE	SELECT A/B	DATA		
		A	B	
H	X	X	X	Z
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

- (1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care
 (2) H = Driving High, L = Driving Low, Z = High Impedance State

9 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μF and 1- μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

10 Layout

10.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

11 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

11.1 Documentation Support

11.1.1 Related Documentation

11.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.3 支持资源

[TI E2E™ 支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《[使用条款](#)》。

11.4 Trademarks

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11.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.6 术语表

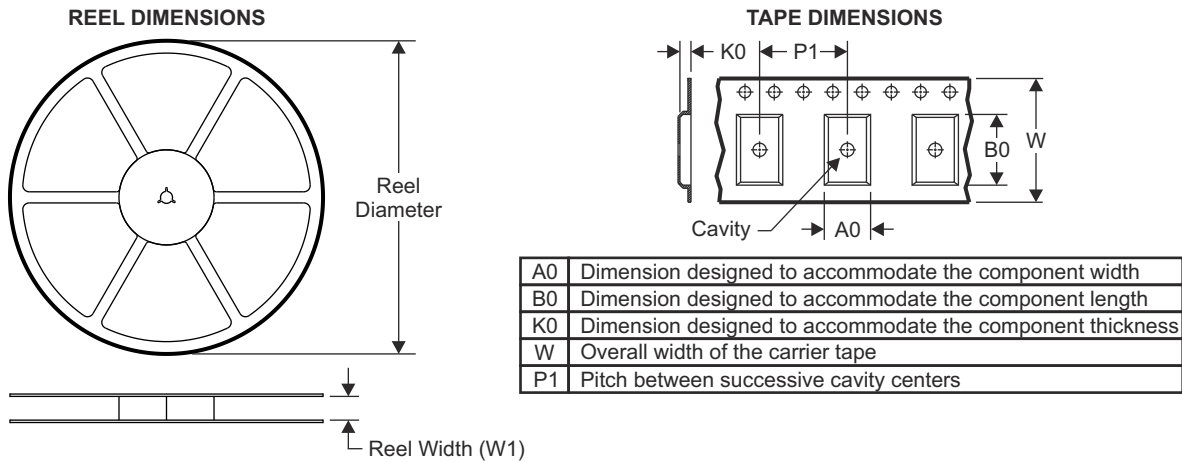
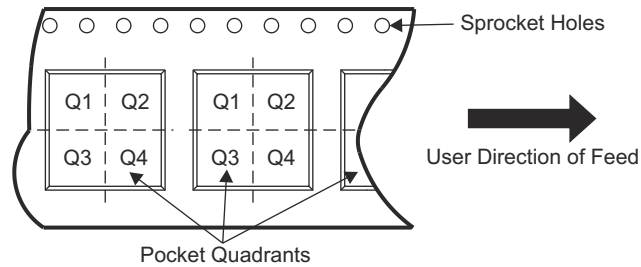
[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

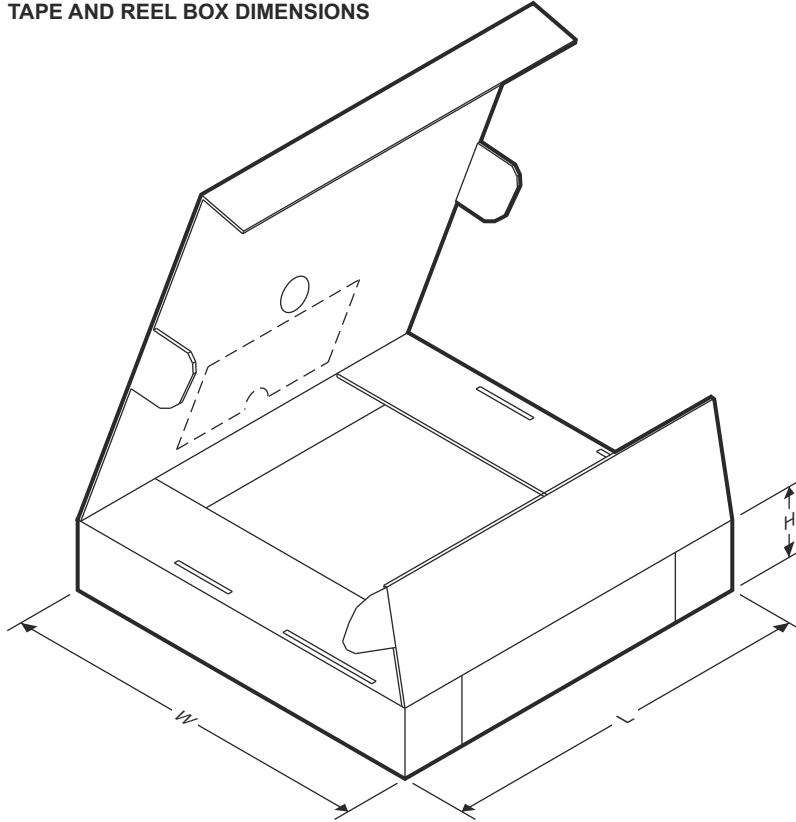
SN54HCT257, SN74HCT257

ZHCSSC5E – NOVEMBER 1988 – REVISED JUNE 2023

12.1 Tape and Reel Information

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant

TAPE AND REEL BOX DIMENSIONS



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)

12.2 Mechanical Data

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HCT257D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85	HCT257	
SN74HCT257DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HCT257	Samples
SN74HCT257N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT257N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

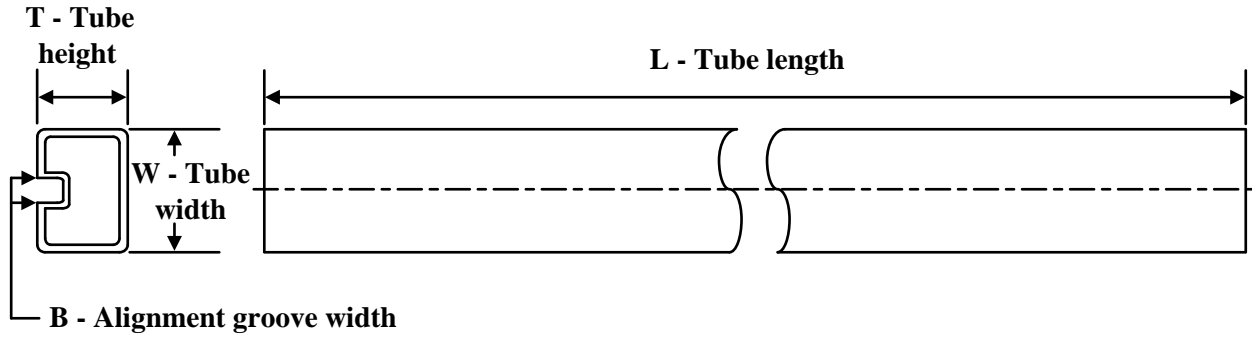

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT257DR	SOIC	D	16	2500	330.0	16.4	6.6	9.3	2.1	8.0	16.0	Q1
SN74HCT257DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT257DR	SOIC	D	16	2500	366.0	364.0	50.0
SN74HCT257DR	SOIC	D	16	2500	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74HCT257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HCT257N	N	PDIP	16	25	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

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